

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Withdrawn) A bonding method in which an electronic component is connected via bumps to a substrate and the electronic component is then packaged on the substrate, comprising the steps of:

performing plasma processing on a surface of the substrate that packages the electronic component, a surface of the electronic component that is connected to the substrate, and a surface of the bumps;

heating the bumps to a temperature lower than a melting point of the bumps; and
compression bonding the substrate and the electronic component via the bumps.

2. (Withdrawn) A bonding method according to claim 1, wherein ultrasonic waves are directed on the bumps when the substrate and the electronic component are being compression bonded via the bumps.

3. (Currently Amended) A bonding stage that packages an electronic component on a substrate, comprising:

a placement member, the placement member having a plasma generating electrode and an electrostatic adhesion electrode, and the placement member having a placement surface on which is placed the substrate or the electronic component; and

a supporting member that supports the placement member, wherein an aperture portion of the supporting member is joined in an airtight seal to the placement member, and a ceramic thermal insulation material is provided in an inner space of the supporting member such that the inner space is substantially filled with the ceramic thermal insulation material.

4. **(Currently Amended)** A bonding stage according to claim 3, wherein the placement member is provided with a heater electrode, and wherein the supporting member is cylindrical.

5. **(Canceled)**

6. **(Currently Amended)** A bonding stage according to claim ~~[[5]]~~ 3, wherein the ceramic thermal insulation material is an Al_2O_3 - SiO_2 - CaO - Li_2O based ceramic thermal insulation material.

7. **(Currently Amended)** A bonding stage according to claim ~~[[5]]~~ 3, wherein the supporting member is formed from stainless steel or an Fe-Ni-Co based alloy.

8. **(Currently Amended)** A bonding stage according to claim ~~[[5]]~~ 3, wherein the placement member is joined to the supporting member via an O-ring or a metal gasket.

9. **(Currently Amended)** An electronic component packaging apparatus comprising:

the bonding stage according to claim ~~[[5]]~~ 3;
a bonding tool positioned above the bonding stage; and
a chamber that houses the bonding stage and the bonding tool.

10. **(Original)** A electronic component packaging apparatus according to claim 9, wherein the bonding tool is provided with an electrostatic adhesion mechanism that electrostatically holds the substrate or the electronic component.

11. **(Original)** A electronic component packaging apparatus according to claim 9, wherein the bonding tool is provided with at least one of a plasma generating electrode and a heater electrode.

12. (Original) A electronic component packaging apparatus according to claim 9, further comprising a pressure application mechanism that applies pressure to the bonding tool.

13. (Original) An electronic component packaging apparatus according to claim 9, wherein the bonding tool is provided with an ultrasonic device that emits ultrasonic waves.